Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6660	inertial with sensor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:12
L2	257	1 and polysilicon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:12
L3	92	2 and silicon adj dioxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:14
L4	11	3 and anchor$4 with pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:48
L5	0	accelometer and achnor adj pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:19
L6	0	accelometer and anchor adj pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:20
L7	14	accelerometer and anchor adj pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:28
L8	10	("2806915" | "3822369" | "5378864" | "5684283" | "5773775" | "6212026" | "6272901" | "6570723" | "6714105").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 16:26

L9	0	713/75.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:27
L10	1262	73/715.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:28
L11	17	10 and sensor and polysilicon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:29
L12	16	10 and sensor and polysilicon and etch$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:29
L13	12	10 and sensor and polysilicon and etch$4 with (via or hole or groove or trench)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:32
L14	1880870	13 and failure or break$4 or weak$7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:32
L15	9	13 and (failure or break$4 or weak$7)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:32
L16	97	200/61.8.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:48

L17	0	16 and sensor and polysilicon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:49
L18	643	438/53.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:49
L19	155	18 and sensor and polysilicon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:49
L20	105	18 and etch$4 with polysilicon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:49
L21	32	20 and anchor$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:52
L22	11	21 and (break$4 or fail$4 or weak$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 16:53
S1	965	wafer and thin$6 and polish$4 and remov$4 with oxide and ((oxide with free) or (oxygen adj free) or (precipitate with free))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/22 18:18
S2	960	wafer and thin$6 and polish$4 and remov$4 with oxide and ((oxide with free) or (oxygen adj free) or (precipitate with free) with (wafer or substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/22 18:19

S35	225	substrate and silicon adj oxide and polysilicon and etch$4 with (notch or groove) and sensor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 14:53
S36	17	S35 and sacrificial and anchor$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 14:55
S37	0	S35 and sacrificial and anchor$6 and weaken$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 14:56
S38	15	S35 and sacrificial and anchor$6 and pressure	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 14:56
S39	15	S35 and sacrificial and anchor$6 and pressure	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 15:07
S40	0	S35 and sacrificial and anchor$6 and pressure and threshold	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 14:59
S41	0	S35 and sacrificial and anchor$6 and pressure with (weak$7 or break$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 14:59
S42	0	S35 and sacrificial and anchor$6 and pressure with (weak$7 or break$4 or fail$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 14:59

| S43 | 8 | S39 and etch$4 with stop | US-PGPUB;
USPAT;
USOCR;
EPO; JPO;
DERWENT;
IBM_TDB | OR | ON | 2005/09/27 16:11 |